US 20170092524A1

(19) **United States**

(12) **Patent Application Publication**

Nakagawa et al.

(10) **Pub. No.: US 2017/0092524 A1**

(43) **Pub. Date: Mar. 30, 2017**

(54) **IMPRINT METHOD, IMPRINT APPARATUS, AND ARTICLE MANUFACTURING METHOD**

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(21) Appl. No.: **15/372,515**

(22) Filed: **Dec. 8, 2016**

Related U.S. Application Data

(63) Continuation of application No. 14/887,472, filed on Oct. 20, 2015, now Pat. No. 9,566,741, which is a continuation of application No. 13/647,667, filed on Oct. 9, 2012, now Pat. No. 9,201,298.

(30) **Foreign Application Priority Data**

Oct. 14, 2011 (JP) 2011-226636
Oct. 2, 2012 (JP) 2012-220209

Publication Classification

(51) **Int. Cl.**

H01L 21/68	(2006.01)
B29C 35/08	(2006.01)
H01L 21/67	(2006.01)
H01L 21/324	(2006.01)
H01L 21/027	(2006.01)
H01L 23/544	(2006.01)
H01L 21/66	(2006.01)
B29C 59/02	(2006.01)
H01L 21/683	(2006.01)

(52) **U.S. Cl.**

CPC ***H01L 21/682*** (2013.01); ***B29C 59/026*** (2013.01); ***B29C 35/0805*** (2013.01); ***H01L 21/6715*** (2013.01); ***H01L 21/6838*** (2013.01); ***H01L 21/67115*** (2013.01); ***H01L 21/0271*** (2013.01); ***H01L 23/544*** (2013.01); ***H01L 22/20*** (2013.01); ***H01L 21/324*** (2013.01); *B29C 2035/0822* (2013.01); *B29L 2031/34* (2013.01)

(57) **ABSTRACT**

An imprint apparatus forms a pattern of an imprint material on a substrate by using a mold. A substrate holding unit holds the substrate by a suction force between the substrate and a holding surface and includes a first suction unit for sucking a rear surface of a first region of the substrate with a first suction force and a second suction unit for sucking a rear surface of a second region of the substrate with a second suction force. A deformation mechanism deforms a shape of the first region in a direction along the holding surface when forming the pattern of the imprint material on the first region. An adjusting unit adjusts the first and second suction forces. The first suction force is less than the second in at least a portion of a period during the deforming of the shape of the first region by the deformation mechanism.

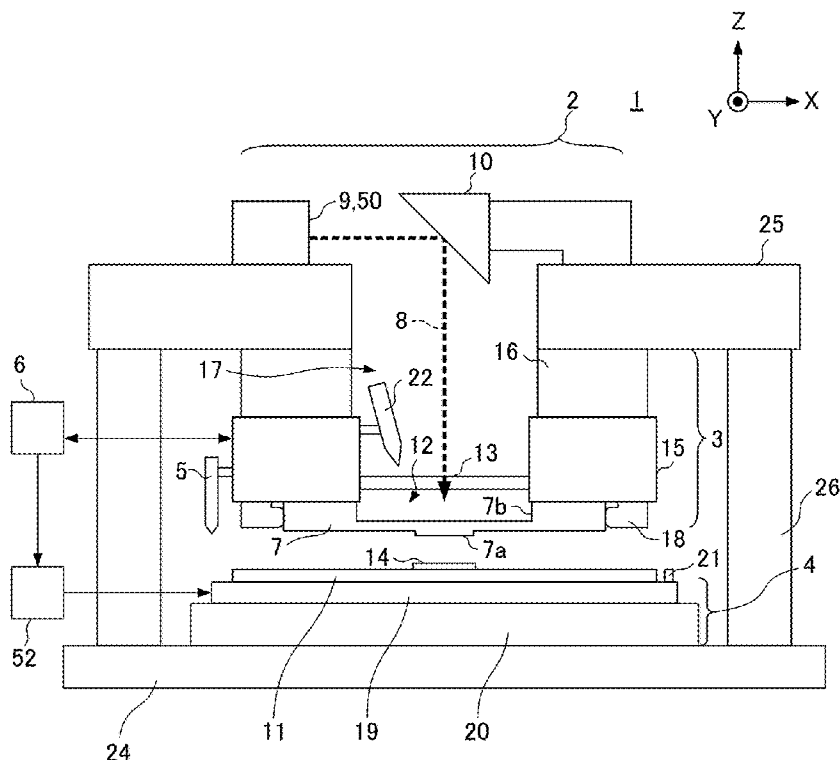


FIG. 1

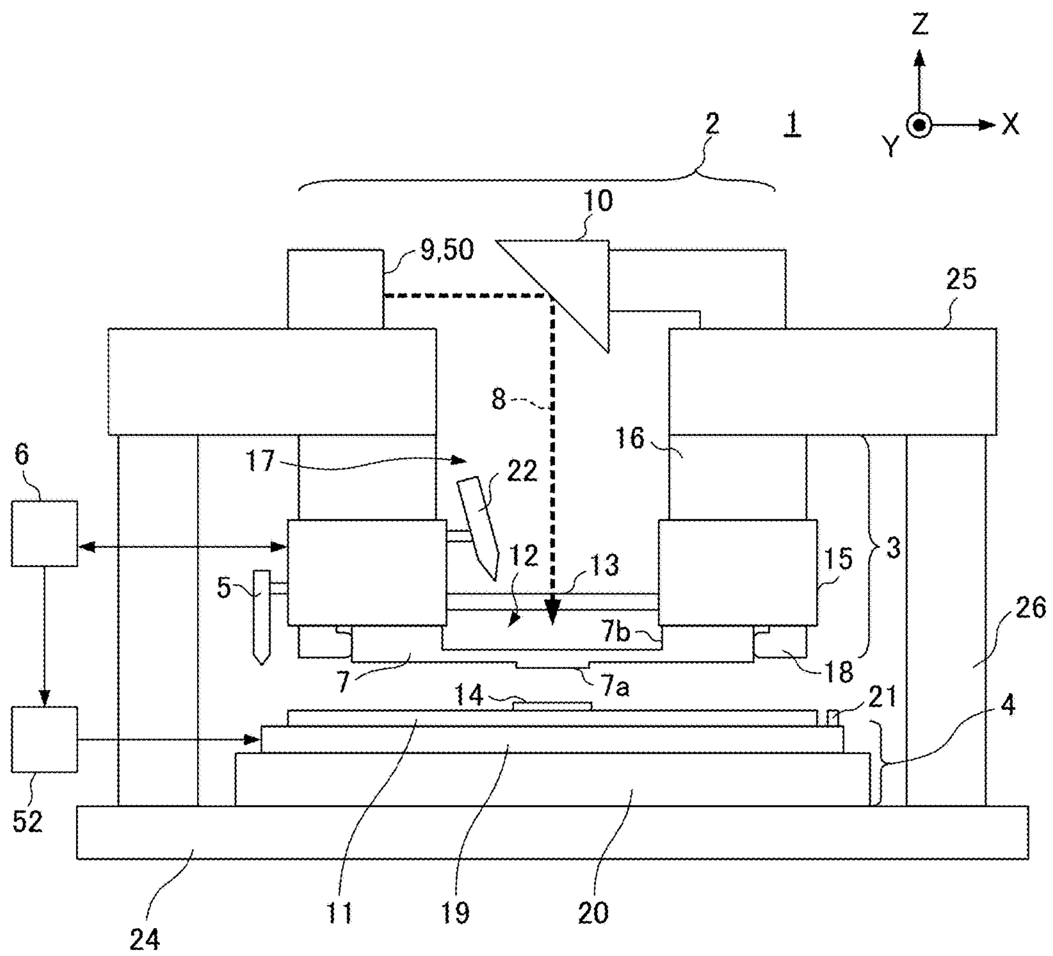


FIG. 2

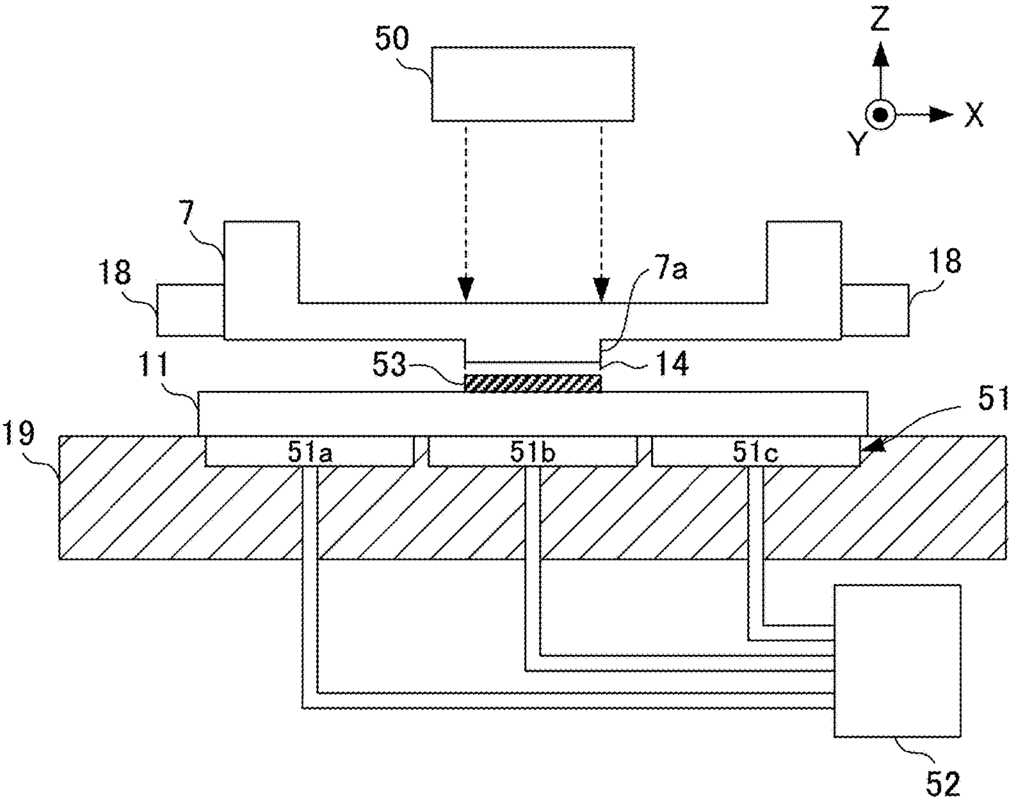
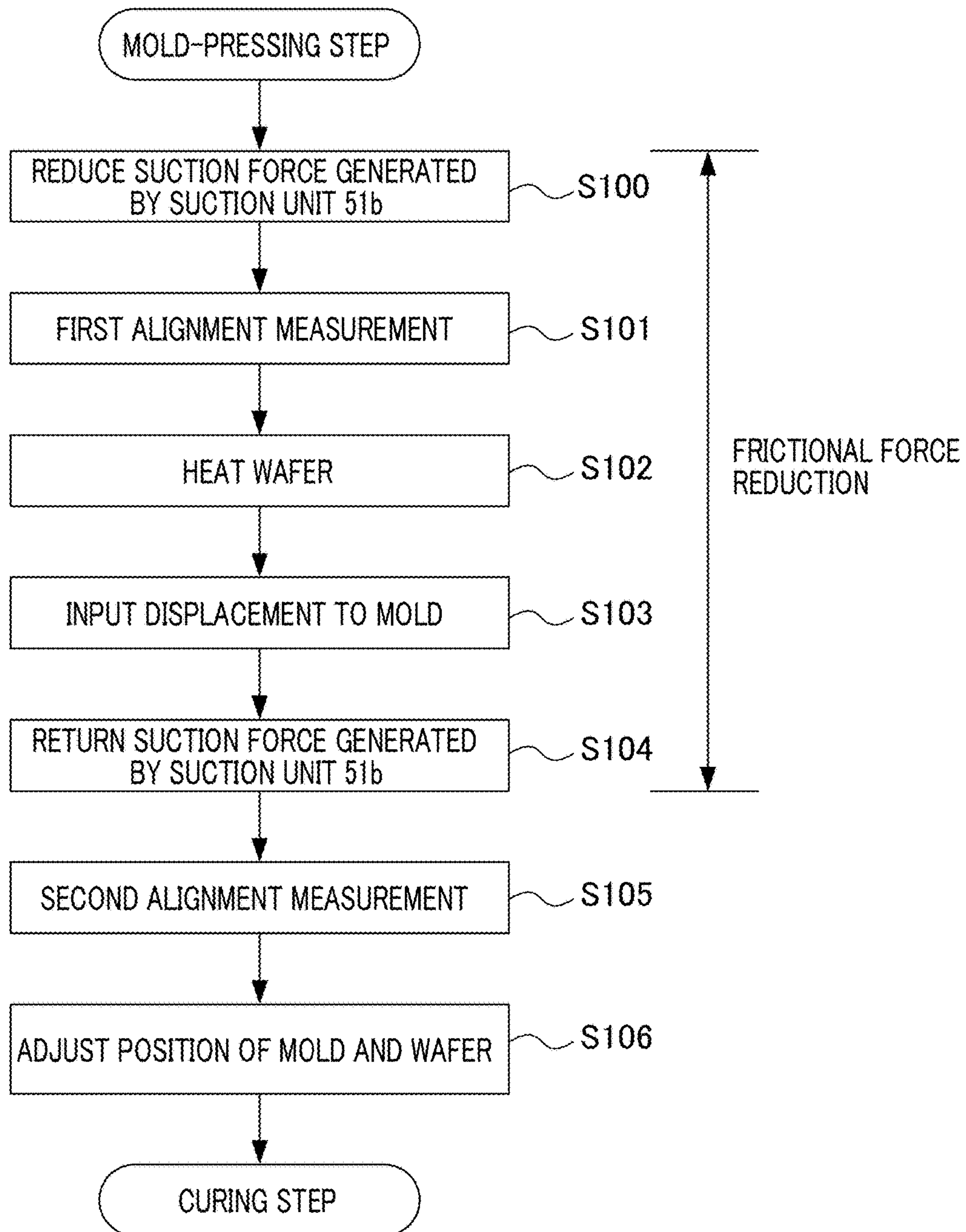


FIG. 3



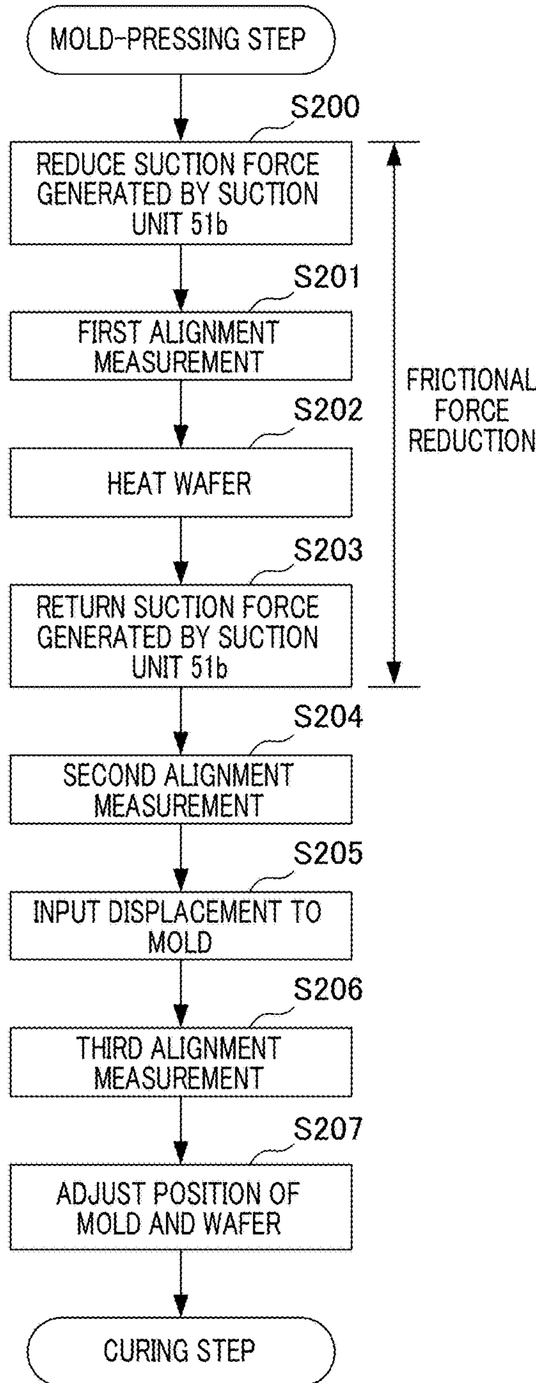


FIG. 4A
MOLD-PRESSING STEP
S200
REDUCE SUCTION FORCE GENERATED BY SUCTION UNIT 51b
S201
FIRST ALIGNMENT MEASUREMENT
S202
HEAT WAFER
S203
RETURN SUCTION FORCE GENERATED BY SUCTION UNIT 51b
FRICTIONAL FORCE REDUCTION
S204
SECOND ALIGNMENT MEASUREMENT
S205
INPUT DISPLACEMENT TO MOLD
S206
THIRD ALIGNMENT MEASUREMENT
S207
ADJUST POSITION OF MOLD AND WAFER
CURING STEP

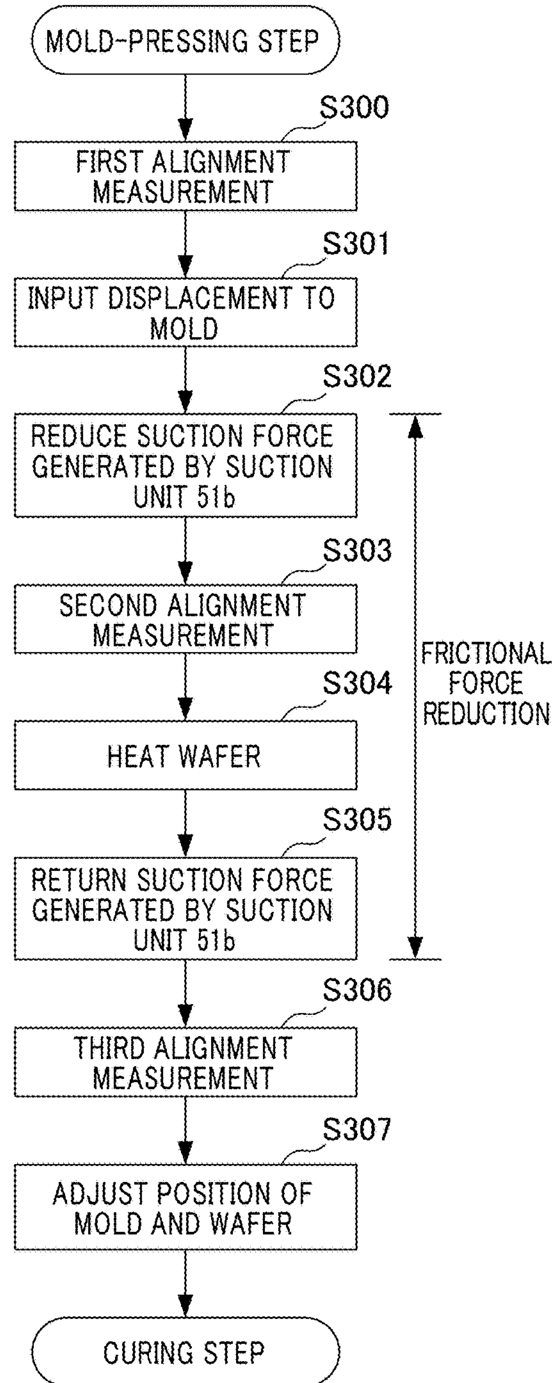


FIG. 4B
MOLD-PRESSING STEP
S300
FIRST ALIGNMENT MEASUREMENT
S301
INPUT DISPLACEMENT TO MOLD
S302
REDUCE SUCTION FORCE GENERATED BY SUCTION UNIT 51b
S303
SECOND ALIGNMENT MEASUREMENT
S304
HEAT WAFER
S305
RETURN SUCTION FORCE GENERATED BY SUCTION UNIT 51b
FRICTIONAL FORCE REDUCTION
S306
THIRD ALIGNMENT MEASUREMENT
S307
ADJUST POSITION OF MOLD AND WAFER
CURING STEP

FIG. 5

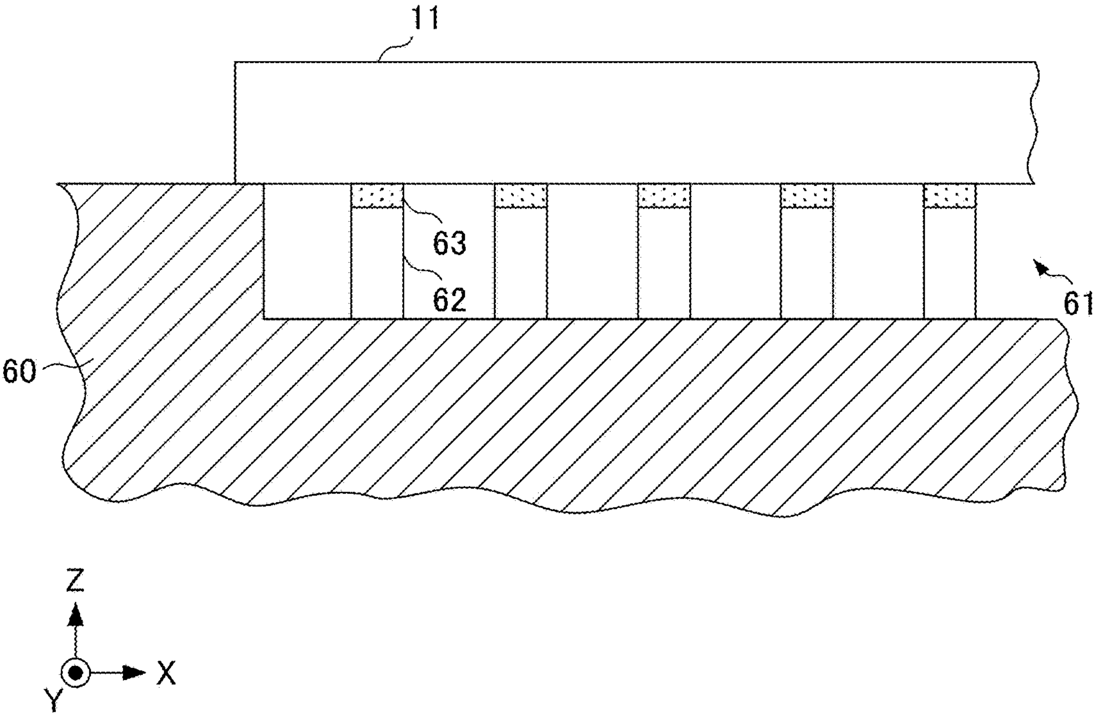


FIG. 6

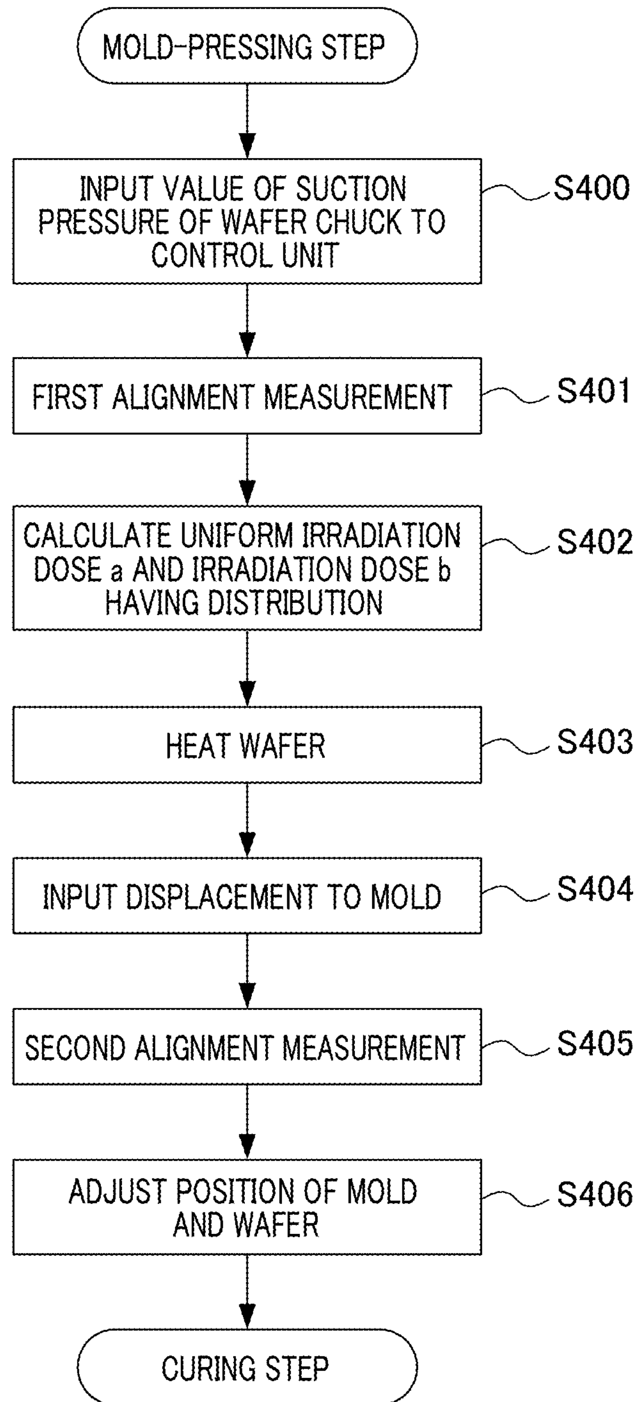
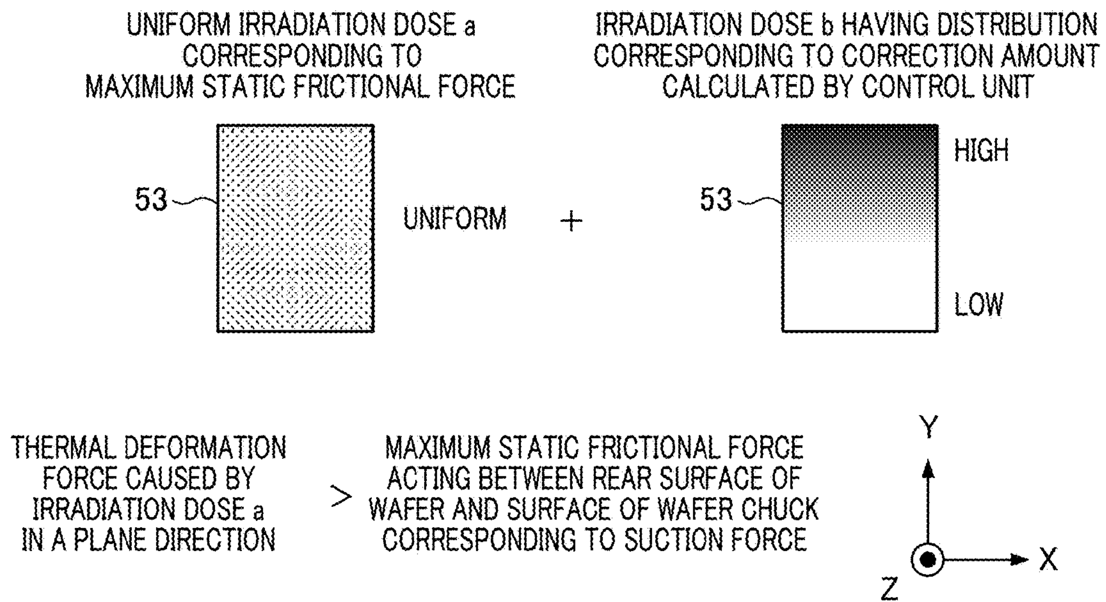


FIG. 7



IMPRINT METHOD, IMPRINT APPARATUS, AND ARTICLE MANUFACTURING METHOD

[0001] This application is a continuation of copending U.S. patent application Ser. No. 14/887,472, filed Oct. 20, 2015, which is a continuation of U.S. patent application Ser. No. 13/647,667, filed Oct. 9, 2012, which matured into U.S. Pat. No. 9,201,298.

[0002] This application also claims the benefit of Japanese Patent Application No. 2011-226636, filed Oct. 14, 2011, and Japanese Patent Application No. 2012-220209, filed Oct. 2, 2012, which are hereby incorporated by reference herein in their entirety.

BACKGROUND OF THE INVENTION

[0003] Field of the Invention

[0004] The present invention relates to an imprint method, an imprint apparatus, and an article manufacturing method.

[0005] Description of the Related Art

[0006] As the demand for microfabrication of semiconductor devices or MEMS increases, not only has conventional photolithography technology, but also, microfabrication technology, in which an uncured resin on a substrate is molded by a mold to thereby form a resin pattern on the substrate, has been receiving attention. This technology is also referred to as “imprint technology”, by which a fine structure with dimensions of a few nanometers can be formed on a substrate. One example of the imprint technology includes a photo-curing method. An imprint apparatus employing the photo-curing method first applies an ultraviolet curable resin (imprint material, photocurable resin) to a shot (imprint region) on a substrate (wafer). Next, the resin (uncured resin) is molded by a mold. After the ultraviolet curable resin is irradiated with ultraviolet light for curing, the cured resin is released from the mold, whereby a resin pattern is formed on the substrate.

[0007] Here, in a series of device manufacturing steps, heat processing in a film formation step, such as sputtering, is performed for a substrate to be subjected to imprint processing. Consequently, the entire substrate may be expanded or reduced, resulting in a change in the shape (size) of the pattern in the direction of two orthogonal in-plane axes. Thus, in an imprint apparatus, the shape of the substrate-side pattern formed on a substrate needs to be matched with the shape of the pattern section formed on a mold when the mold is pressed against the resin on the substrate. In a conventional exposure apparatus, such shape correction (magnification correction) can be ensured by changing the size of each shot during exposure processing by changing the reduction magnification of a projection optical system in accordance with the magnification of the substrate or by changing the scanning speed of a substrate stage. However, the imprint apparatus does not have a projection optical system and the mold is brought into direct contact with the resin on the substrate, and thus, it is difficult to perform such correction. Hence, the imprint apparatus employs a shape correction mechanism (magnification correction mechanism) that physically deforms a mold by imparting an external force to the sides of the mold or by expanding the mold by heating.

[0008] For example, assume a case wherein the imprint apparatus is applied to a manufacturing step of manufacturing a semiconductor device having a half-pitch of about 32 nm. At this time, according to ITRS (International Technology Roadmap for Semiconductors), the superposition accuracy is 6.4 nm. In order to accommodate this, shape correction also needs to be performed with an accuracy of a few nm or less. On the other hand, the mold (pattern section) used in the imprint apparatus may also be distorted by the following causes. For example, the pattern surface of a mold is directed upward when the mold is being prepared, whereas the pattern surface thereof is directed downward when the mold is used (during pressing). Thus, the pattern section may be deformed upon usage under the influence of gravity. Although the pattern section is typically formed by a drawing apparatus using an electron beam, or the like, the pattern section may also be distorted due to distortion aberration of the optical system of the drawing apparatus during formation thereof. Furthermore, even if the pattern section can be prepared without distortion, the occurrence of distortion in a substrate-side pattern may result in an adverse effect on the superposition accuracy. Accordingly, in order to suppress such distortion (deformation) of the mold and to improve superposition accuracy, Japanese Patent Laid-Open No. 2004-259985 discloses a pattern forming apparatus that controls the temperature of a mold and a substrate by means of a retention temperature control unit, and corrects the shape of the mold or the substrate by generating desired thermal deformation in the mold or the substrate.

[0009] In the conventional imprint apparatus, however, a substrate is held by a substrate holding unit, such as a wafer chuck, with the bottom surface of the substrate restricted thereto. Thus, even if thermal deformation is generated on the substrate under temperature control disclosed in Japanese Patent Laid-Open No. 2004-259985, it is still difficult to sufficiently change the shape of the substrate-side pattern relative to the shape of the pattern section. Accordingly, an imprint apparatus is desired that is capable of improving superposition accuracy between a mold and a resin on a substrate by readily implementing not only the correction of the shape of the mold, but also, the correction of the shape of the substrate (including the substrate-side pattern) relative to the shape of the mold.

SUMMARY OF THE INVENTION

[0010] The present invention provides an imprint apparatus that is advantageous for improving superposition accuracy between a mold and resin on a substrate.

[0011] According to one aspect, the present invention provides an imprint apparatus for forming a pattern of an imprint material on a substrate by using a mold that includes a substrate holding unit configured to hold the substrate by acting a suction force between the substrate and a holding surface, the substrate holding unit including a first suction unit for sucking a rear surface of a first region of the substrate with a first suction force and a second suction unit for sucking a rear surface of a second region of the substrate different from the first region of the substrate with a second suction force, a deformation mechanism configured to deform a shape of the first region in a direction along the holding surface when forming the pattern of the imprint material on the first region, and an adjusting unit configured to adjust the first suction force and the second suction force. The adjusting unit adjusts the first suction force to be less than the second force in at least a portion of a period during the deforming of the shape of the first region by the deformation mechanism.

[0012] According to another aspect, the present invention provides a method of manufacturing an article including the steps of (a) forming a pattern of an imprint material on a substrate using an imprint apparatus for forming the pattern on the substrate by using a mold, (b) processing the substrate on which the pattern is formed by the forming, and (c) manufacturing the article from the processed substrate. The imprint apparatus includes (i) a substrate holding unit configured to hold the substrate by acting as a suction force between the substrate and a holding surface, the substrate holding unit including a first suction unit for sucking a rear surface of a first region of the substrate with a first suction force and a second suction unit for sucking a rear surface of a second region of the substrate different from the first region of the substrate with a second suction force, (ii) a deformation mechanism configured to deform a shape of the first region in a direction along the holding surface when forming the pattern of the imprint material on the first region, and (iii) an adjusting unit configured to adjust the first suction force and the second suction force. The adjusting unit adjusts the first suction force to be less than the second force in at least a portion of a period during the deforming of the shape of the first region by the deformation mechanism.

[0013] Further features of the present invention will become apparent from the following description of exemplary embodiments with reference to the attached drawings.

BRIEF DESCRIPTION OF THE DRAWINGS

[0014] FIG. **1** is a diagram illustrating the configuration of an imprint apparatus according to a first embodiment of the present invention.

[0015] FIG. **2** is a diagram illustrating the configuration of a wafer stage according to the first embodiment.

[0016] FIG. **3** is a flowchart illustrating the sequence of operations according to the first embodiment.

[0017] FIG. **4**A is a flowchart illustrating the sequence of operations according to a second embodiment.

[0018] FIG. **4**B is a flowchart illustrating a variant example of the sequence of operations shown in FIG. **4**A.

[0019] FIG. **5** is a diagram illustrating the configuration of a wafer stage according to a third embodiment.

[0020] FIG. **6** is a flowchart illustrating the sequence of operations according to a fourth embodiment.

[0021] FIG. **7** is a diagram illustrating the irradiation dose of light according to the fourth embodiment.

DESCRIPTION OF THE EMBODIMENTS

[0022] Hereafter, preferred embodiments of the present invention will be described with reference to the accompanying drawings.

First Embodiment

[0023] First, a description will be given of the configuration of an imprint apparatus according to a first embodiment of the present invention. FIG. **1** is a schematic diagram illustrating the configuration of an imprint apparatus **1** of the present embodiment. The imprint apparatus **1** is an apparatus that molds an uncured resin on a wafer (on a substrate), i.e., a substrate to be treated, using a mold, to thereby form a resin pattern on the wafer, which is used in the manufacture of devices, such as semiconductor devices, and the like, as articles. Note that the imprint apparatus of the present embodiment is an apparatus employing a photo-curing method. In the following drawings, a description will be given in which the Z axis is aligned parallel to the optical axis of an irradiation system that irradiates a resin on a wafer with ultraviolet light, and mutually orthogonal axes, X and Y, are aligned in a plane perpendicular to the Z axis. The imprint apparatus **1** includes a light irradiation unit **2**, a mold holding mechanism **3**, a wafer stage **4**, an application unit **5**, and a control unit **6**.

[0024] The light irradiation unit **2** irradiates a mold **7** with ultraviolet light **8** during imprint processing. The light irradiation unit **2** is constituted by a light source **9** and an optical element **10** that adjusts the ultraviolet light **8** emitted from the light source **9** to light suitable for imprinting. Note that, in the present embodiment, the light irradiation unit **2** is installed for employing a photo-curing method. If, however, a thermosetting method is employed, a heat source unit for curing a thermosetting resin may be installed, instead of the light irradiation unit **2**. Furthermore, the light irradiation unit **2** includes a heating light source **50** that functions as a heating mechanism (substrate deformation mechanism) for heating a wafer **11** by irradiating the wafer **11** with light in addition to light from the light source **9**. The light irradiated by the heating light source **50** is light near the wavelength range of infrared light, to which a photocurable resin is not sensitive. The heating mechanism also includes an adjuster that forms a predetermined irradiation dose distribution of light. In the present embodiment, a description will be given on the assumption that the heating light source **50** is integrated with the adjuster. Note that the adjuster may be provided separately from the heating light source **50**. For example, a liquid crystal device including a plurality of liquid crystal elements arranged in a region irradiated with light emitted from the heating light source **50** or a mirror device, including a plurality of mirrors arranged in a region irradiated with light, may also be used. Here, the mirror device may also be referred to as a "digital mirror device" or a "micro mirror device". The liquid crystal device is capable of forming a predetermined irradiation dose distribution by independently adjusting voltages to be applied to a plurality of liquid crystal elements, whereas the mirror device is capable of forming a predetermined irradiation dose distribution by independently adjusting the surface directions of a plurality of mirrors.

[0025] The outer peripheral shape of the mold **7** is rectangular, and the mold **7** includes a pattern section (e.g., a circuit pattern, or the like) **71**, in which the concave and convex pattern is three-dimensionally formed on the surface of the facing wafer **11**. Also, the material of the mold **7** is a material such as quartz, or the like, through which the ultraviolet light **8** can pass. Furthermore, the mold **7** may be of a shape in which a cavity (concave portion) **7*b*** for facilitating the deformation of the mold **7** is formed on the surface onto which the ultraviolet light **8** is irradiated. The cavity **7*b*** has a circular planar shape, and the thickness (depth) of the cavity **7*b*** is appropriately set, depending on the size or the material of the mold **7**. A light transmission member **13** may also be installed within an aperture region **17** in the mold holding mechanism **3**, to be described below, such that a space **12** enclosed by a part of the aperture region **17** and the cavity **7*b*** is sealed, and the pressure in the space **12** may be adjusted by a pressure adjusting device (not shown). For example, the pressure adjusting device sets the pressure in the space **12** to be higher than the external

pressure when the mold **17** is pressed against a resin **14** on the wafer **11**, so that the pattern section **7***a* is deflected into a convex shape toward the wafer **11**, and the pattern section **7***a* is brought into contact with the resin **14** from the central portion of the pattern section **7***a*. With this arrangement, gas (air) is prevented from being entrapped between the pattern section **7***a* and the resin **14**, so that the resin **14** can be filled in every corner of the convex and concave portion of the pattern section **7***a*.

[0026] The mold holding mechanism **3** has a mold chuck **15** that holds the mold **7** by suctioning/attracting the mold **7** using a vacuum suction force/and an electrostatic attraction force, and a mold drive mechanism **16** that holds the mold chuck **15** and moves the mold **7** (the mold chuck **15**). Also, each of the mold chuck **15** and the mold drive mechanism **16** has the aperture region **17** at the central portion (the inside thereof), such that the ultraviolet light **8**, emitted from the light source **9** of the light irradiation unit **2**, is irradiated toward the wafer **11**. Furthermore, the mold holding mechanism **3** has a magnification correction mechanism (mold deformation mechanism) **18** that corrects the shape of the mold **7** (the pattern section **7***a*) by imparting an external force or a displacement to the side surface of the mold **7**. The magnification correction mechanism **18** is installed at the mold **7** holding side of the mold chuck **15**. The magnification correction mechanism **18** deforms the shape of the mold **7**, to thereby match the shape of the pattern section **7***a* formed on the mold **7** relative to the shape of the area on the substrate (substrate-side pattern area) **53** where the pre-existing pattern is formed. If it is difficult to match the shape of the pattern section **7***a* relative to the shape of the substrate-side pattern area **53**, the magnification correction mechanism **18** may also be adapted to make the shapes of both patterns close to each other (i.e., to reduce a shape differential between the two). While the one substrate-side pattern area **53** is shown in the figure, a plurality of substrate-side pattern areas are formed on the wafer **11**.

[0027] The mold drive mechanism **16** moves the mold **7** in the Z-axis direction so as to relatively bring the mold **7** into contact with the resin **14** on the wafer **11**, or to release the mold **7** from the resin **14**. Examples of an actuator employable for the mold drive mechanism **16** include a linear motor, an air cylinder, and the like. Also, the mold drive mechanism **16** may be constituted by a plurality of drive systems, such as a coarse movement drive system, a fine movement drive system, and the like, in order to accommodate position of the mold **7** with high accuracy. Furthermore, the mold drive mechanism **16** may have a position adjustment function for adjusting the position of the mold **7**, not only in the Z-axis direction, but also, in the X-axis direction, the Y-axis direction, or the θ (rotation about the Z axis) direction, a tilt function for correcting the tilt of the mold **7**, and the like. The contacting operation and the releasing operation performed by the imprint apparatus **1** may be realized by moving the mold **7** in the Z-axis direction, may be realized by moving the wafer stage **4** in the Z-axis direction, or may also be realized by moving both the mold **7** and the wafer stage **4** relative to each other.

[0028] The wafer **11** is, for example, a single crystal silicon substrate or an SOI (Silicon on Insulator) substrate, and an ultraviolet curable resin (hereafter referred to as "resin") **14**, which is molded by the pattern section **7***a* formed in the mold **7**, is applied on the treatment surface of the wafer **11**.

[0029] The wafer stage **4** holds the wafer **11** and executes position matching between the mold **7** and the resin **14** before, or while the mold **7** is brought into contact with the resin **14** on the wafer **11**. The wafer stage **4** has a wafer chuck (substrate holding unit) **19**, on which a holding surface for holding the wafer **11** is formed, and a stage drive mechanism **20** that holds the wafer chuck **19** by a mechanical unit and is movable in the XY plane.

[0030] FIG. **2** is a schematic cross-sectional diagram illustrating the wafer chuck **19** of the present embodiment and the configuration of the peripheral portion thereof. The wafer chuck **19** includes a plurality of suction units **51** that holds the rear surface of the wafer **11** by suction. As shown in FIG. **2**, the suction units **51** may be constituted by, for example, three suction units **51***a* to **51***c*. These suction units **51***a* to **51***c* are connected to a pressure adjusting device **52** separate from the aforementioned pressure adjusting device, and function as a frictional force adjusting mechanism that adjusts the frictional force acting between the rear surface of the wafer **11** corresponding to a region including the substrate-side pattern area **53** and the surface of the wafer chuck **19**. The pressure adjusting device **52** adjusts the pressure to reduce the pressure between the wafer **11** and the suction units **51**, to thereby generate a suction force. Consequently, the pressure adjusting device **52** is capable of independently changing pressure values (suction forces) applied by the suction units **51***a* to **51***c*, while holding the wafer **11** on the surface of the wafer chuck **19**. Note that the number of divided suction units **51** is not limited to three, but may be any number. Also, the wafer chuck **19** has a reference mark **21** that is used when the mold **7** is subjected to alignment on the surface thereof.

[0031] Examples of an actuator employable for the stage drive mechanism **20** include a linear motor. The stage drive mechanism **20** may also be constituted by a plurality of drive systems, such as a coarse movement drive system, a fine movement drive system, and the like, with respect to the X-axis and Y-axis directions. Furthermore, the stage drive mechanism **20** may have a drive system for adjusting the position of the wafer **11** in the Z-axis direction, a position adjustment function for adjusting the position of the wafer **11** in the **0** direction, a tilt function for correcting the tile of the wafer **11**, and the like.

[0032] The application unit **5** applies the resin (uncured resin) **14** to the wafer **11**. Here, the resin **14** is a photocurable resin (imprint material) having the property of being cured by receiving irradiation of the ultraviolet light **8**, and is appropriately selected depending on various conditions, such as the manufacturing process of semiconductor devices, or the like. The amount of the resin **14** to be ejected from the ejection nozzle of the application unit **5** is also appropriately determined by a desired thickness of the resin **14** to be formed on the wafer **11**, the density of the pattern to be formed, or the like.

[0033] The control unit **6** may control the operation, adjustment, and the like, of the components of the imprint apparatus **1**. The control unit **6** is constituted by a computer, or the like, and is connected to the components of the imprint apparatus **1** through a line so as to execute control of the components by a program, or the like. The control unit **6** of the present embodiment may control the operation of at least the light irradiation unit **2**, the wafer stage **4**, and the pressure adjusting device **52**. Note that the control unit **6** may be integrated with the rest of the imprint apparatus **1**

(provided in a common housing) or may be provided separately from the rest of the imprint apparatus **1** (provided in a separate housing).

[0034] Also, the imprint apparatus **1** includes an alignment measurement system **22** that measures a positional shift between an alignment mark formed on the wafer **11** and an alignment mark formed on the mold **7** in each direction of the X-axis and the Y-axis as wafer alignment. Furthermore, the imprint apparatus **1** includes a base surface plate **24**, on which the wafer stage **4** is placed, a bridge surface plate **25** that fixes the mold holding mechanism **3**, and a strut **26** that is extended from the base surface plate **24**, and supports the bridge surface plate **25**. Furthermore, the imprint apparatus **1** includes a mold conveyance mechanism (not shown) that conveys the mold **7** from the exterior of the apparatus to the mold holding mechanism **3** and a substrate conveyance mechanism (not shown) that conveys the wafer **11** from the exterior of the apparatus to the wafer stage **4**.

[0035] Next, a description will be given of imprint processing performed by the imprint apparatus **1**. First, the control unit **6** places the wafer **11** on the wafer chuck **19** of the wafer stage **4** using the substrate conveyance mechanism, holds the wafer **11** on the holding surface of the wafer chuck **19** (holding step), and then moves the wafer stage **4** to the application position of the application unit **5**. Then, as an application step, the application unit **5** applies the resin **14** to the substrate-side pattern area (a shot area) **53**. Next, the control unit **6** moves the wafer stage **4** such that the substrate-side pattern area **53** on the wafer **11** is placed in a position directly below the pattern section **7***a* formed in the mold **7**. Next, the control unit **6** drives the mold drive mechanism **16** so as to press the mold **7** against the resin **14** on the wafer **11** (mold-pressing step) so that the mold **7** is brought into contact with the resin **14** (contacting step). During the contacting step, the resin **14** is filled in the convex and the concave pattern of the pattern section **7***a*. Under this condition, as a curing step, the light irradiation unit **2** emits the ultraviolet light **8** from the rear surface (the top surface) of the mold **7**, and cures the resin **14** by the ultraviolet light **8** that has been transmitted through the mold **7**. Then, after the resin **14** is cured, the control unit **6** drives the mold drive mechanism **16** again, to thereby release the mold **7** from the resin **14** (mold-releasing step). By the aforementioned steps, a three-dimensionally shaped pattern (layer) of the resin **14** following the convex and concave pattern of the pattern section **7***a* is formed on the surface of the substrate-side pattern area **53** on the wafer **11**. Such a sequence of imprint operations is conducted two or more times, while the substrate-side pattern area **53** is changed under the drive of the wafer stage **4**, to thereby be able to form a plurality of patterns of the resin **14** on one wafer **11**.

[0036] Here, a description will be given of the suction control by means of the wafer chuck **19** when a pattern is formed on the wafer **11** for a predetermined shot. FIG. **3** is a flowchart illustrating the sequence of operations from the mold-processing step to the curing step performed by the imprint apparatus **1**. At this time, a shot to be processed is located at the central portion of the wafer **11**, and, as shown in FIG. **2**, the position is intended to correspond to the suction unit **51***b* provided in the wafer chuck **19**. In this case, the control unit **6** causes the pressure adjusting device **52** to reduce only the suction force generated by the suction unit **51***b*, while maintaining the suction force generated by the suction units **51***a* and **51***c* prior to the correction of the shape of the pattern section **7***a* and the wafer **11** (step S **100**). For example, the suction pressure of the suction unit **51***b* may be ambient pressure. If the suction pressure of the suction unit **51***b* is less than the suction force generated by the suction units **51***a* and **51***c*, the suction pressure of the suction unit **51***b* may be ambient pressure or less. When the adjusting range of the irradiation dose of light emitted from the heating light source **50** is set in advance, the suction pressure of the suction unit **51***b* may be set such that the thermal deformation force W acting o the substrate-side pattern area **53** in a direction along the surface of the wafer **11** is greater than the maximum static frictional force F acting between the rear surface of the wafer **11** and the suction unit **51***b*. When the temperature rise of the substrate-side pattern area **53** is give as "ΔT", the thermal expansion coefficient thereof is given as "α", and the modulus of elasticity thereof is given as "E", all of which are determined depending on the irradiation dose, the thermal stress "σ" can be approximately expressed as the products of α, E, and ΔT. The thermal deformation force W, depending on the thermal stress "a" and the cross-sectional area "S", acts on the substrate-side pattern area **53**. When the maximum static frictional coefficient is given as "p." and the vertical direction depending on the suction pressure is given as "N", the maximum static frictional force F can be expressed as the product of μ and N. In other words, it is only necessary to satisfy the relationship of $F<W$. Note that the region on the wafer **11** held by the suction unit **51***b* may be a region including at least the substrate-side pattern area **53** where the pattern is pre-formed on the wafer **11**. Next, the control unit **6** causes the alignment measurement system **22** to measure the positions of the mold **7** and the wafer **11** in the X-axis and the Y-axis directions (first alignment measurement, step S**101**), and acquires information regarding differences between the shape of the pattern section **7***a* and the shape of the substrate-side pattern area **53** (acquiring step). However, when it is desired to correct only the shape of the substrate-side pattern area **53** formed on the wafer **11**, the control unit **6** may acquire only information regarding the shape of the substrate-side pattern area **53**. Then, the control unit **6** calculates the correction amount to a positional shift between the pattern section **7***a* and the substrate-side pattern area **53** based on the measurement result obtained in step S**101**. Next, the control unit **6** causes the heating light source **50** of the light irradiation unit **2** to heat the wafer **11** by irradiating the wafer **11** with light (deformation step: step S**102**), and causes the magnification correction mechanism **18** to operate for inputting displacement (mold-deformation step: step S**103**), and thus, the shapes of the pattern section **7***a* and the substrate side pattern area **53** are corrected. Since the maximum static frictional force acting between the rear surface of the wafer **11** corresponding to the substrate-side pattern area **53** and the holding surface is reduced, as described above, the thermal deformation force greater than the maximum static frictional force F can be applied to the wafer **11** in a direction along the surface thereof. Also, a temperature distribution is imparted to the substrate-side pattern area **53** by irradiating the substrate-side pattern area **53** with light having an irradiation dose distribution, whereby the shape of various components can be corrected. For example, among the calculated correction amount, a low-order component (e.g., a trapezoidal component) is corrected by heating the wafer **11** and a high-order component is corrected by displacement input, whereby the shape

of the pattern section **7***a* can be preferably matched with the shape of the substrate-side pattern area **53**. When the shape of the pattern section **7***a* is matched with the shape of the substrate-side pattern area **53**, as a result of correction, the control unit **6** causes the pressure adjusting device **52** to reduce the suction pressure of the suction unit **51***b* again, so as to return the suction force generated by the suction unit **51***b* back to the level of the suction force generated by the suction units **51***a* and **51***c* (step S**104**). Next, the control unit **6** causes the alignment measurement system **22** to measure the positions of the mold **7** and the wafer **11**, again, in the X-axis and the Y-axis directions (second alignment measurement: step S**105**). Here, if it is determined that a positional shift is present between the mold **7** and the wafer **11**, the control unit **6** causes the mold drive mechanism **16** or the stage drive mechanism **20** to drive, to perform position adjustment between the mold **7** and the wafer **11** (step S**106**). Then, the control unit **6** proceeds to the next process in the curing step.

[0037] The step of reducing the suction force generated by the suction unit **51***b* in step S**100** may be started, not only prior to the first alignment measurement in step S**101**, but also, after the first alignment measurement. It is preferable that the step of reducing the suction force generated by the suction unit **51***b* is performed prior to or during the deforming step of heating a substrate. In step S**102**, the correction of the shape of the substrate-side pattern area **53** on the wafer **11** is performed by heating due to the irradiation of light from the heating light source **50**, but the present invention is not limited thereto. For example, in a substrate deformation mechanism, instead of the heating light source **50**, a separately provided external force applying mechanism may impart an external force or input displacement in a planar direction directly to the wafer **11**, to thereby perform the correction of the shape of the substrate-side pattern area **53**. Furthermore, the shape of the substrate-side pattern area **53** may be matched with the shape of the pattern section **7***a* by performing shape correction only due to the heating of the wafer **11** in step S**102**, without performing the displacement input to the mold **7** in step S**103**. Note that steps S**102** and step S**103** may be performed inversely or in parallel. Also, it is preferable that the step of recovering the suction force generated by the suction unit **5** lb is performed after the deforming step, and prior to the mold-releasing step.

[0038] As described above, in the imprint apparatus **1**, the suction force generated by the suction unit **5** lb is reduced during a period from the mold-pressing step to the curing step, to thereby reduce a frictional force between the suction unit **51***b* and the rear surface of the wafer **11**, including at least the substrate-side pattern area **53**. Specifically, during the thermal deformation of the substrate-side pattern area **53** by the heating light source **50** of the light irradiation unit **2**, a frictional force acting between the wafer chuck **19** and the rear surface of the wafer **11**, corresponding to the substrate-side pattern area **53**, is reduced more than when the substrate-side pattern area **53** is not subjected to thermal deformation. Thus, the substrate-side pattern area **53** can be efficiently deformed by heating. In other words, the substrate-side pattern area **53** can be deformed by heating without an unnecessary increase in irradiation dose, and thus, an unnecessary rise in temperature of the peripheral members can be suppressed. Consequently, the adverse effect on superposition accuracy between the mold **7**, and the resin **14** on the wafer **11**, can be suppressed. Furthermore, at this time, the suction force generated by other suction units **51***a* and **51***c* remains maintained. Consequently, the wafer **11** is firmly fixed on the wafer chuck **19** by suction, even if the wafer **11** is subjected to thermal deformation, and thus, displacement of the entire wafer **11** is suppressed. There is no need to reduce a frictional force at all times during thermal deformation, but a frictional force may be reduced in at least a portion of the period during thermal deformation.

[0039] As described above, according to the present embodiment, the imprint apparatus **1**, which is advantageous for improving superposition accuracy between the mold **7** and the resin **14** on the wafer **11**, may be provided.

Second Embodiment

[0040] Next, a description will be given of an imprint apparatus according to a second embodiment of the present invention. The imprint apparatus of the present embodiment has the same configuration as that of the first embodiment, but the sequence of operations from the mold-pressing step to the curing step is changed. FIGS. **4**A and **4**B are flowcharts illustrating the sequence of operations from the mold-pressing step to the curing step performed by the imprint apparatus **1** according to the present embodiment. First, in the example shown in FIG. **4**A, after the mold-pressing step, the control unit **6** causes the magnification correction mechanism **18** to perform the displacement input to the mold **7** in step S **103**, in the sequence of operations of the first embodiment shown in FIG. **3**, after the second alignment measurement in step S**105** (step S**205**). Here, given that the alignment measurement in step S**201** is the first alignment measurement, a step corresponding to a step S**105**, shown in FIG. **3**, is the second alignment measurement shown in FIG. **4**A (step S**204**). In this case, the control unit **6** causes the alignment measurement system **22** to perform the third alignment measurement the same as the second alignment measurement, again, after step S**205** (step S**206**). Note that the third alignment measurement may be omitted by using the value obtained by the second alignment measurement. The processes in other steps are the same as those in the first embodiment.

[0041] On the other hand, in the example shown in FIG. **4**B, after the mold-pressing step, the control unit **6** causes the magnification correction mechanism **18** to perform the displacement input to the mold **7** in step S**103** in the sequence of operations of the first embodiment shown in FIG. **3**, prior to the process of reducing the suction force generated by the suction unit **51***b* in step S**100** (step S**301**). In this case, the control unit **6** causes the alignment measurement system **22** to perform the first alignment measurement, which is a process corresponding to step S**101** shown in FIG. **3**, prior to step S**301** (step S**300**). Also, the control unit **6** starts the process of reducing the suction force generated by the suction unit **51***b*, which corresponds to step S**100** shown in FIG. **3**, after step S**301** (step S**302**). Then, after step S**304**, corresponding to step S**102** shown in FIG. **3**, which is the correction of the shape of the substrate-side pattern area **53** on the wafer **11**, the control unit **6** raises the suction force generated by the suction unit **51***b* again (step S**305**). The processes in the other steps are the same as those in the first embodiment. According to the present embodiment, as shown in FIGS. **4**A and **4**B, the displacement input to the mold **7** by means of the magnification correction mechanism

18 is not performed while a frictional force is being reduced. Thus, the same effects as those in the first embodiment may be provided. In addition, unnecessary positional shift or unnecessary deformation of the wafer **11**, in association with deformation of the mold **7** upon inputting of displacement, can be further suppressed.

Third Embodiment

[0042] Next, a description will be given of an input apparatus according to a third embodiment of the present invention. In the imprint apparatus of the present embodiment, the configuration of the suction units **51** provided in the wafer chuck **19** according to the first embodiment is changed. FIG. **5** is a schematic cross-sectional diagram illustrating an enlarged portion of the suction unit **51** (**51***a*) provided in the wafer chuck **19** according to the present embodiment. The suction unit **51** has a plurality of suction pins **60** within the suction region, and a low-friction member **61** made of a low-friction material having a low friction coefficient against the wafer **11** is provided at the tip surface of each suction pin **60**, i.e., the surface in contact with the rear surface of the wafer **11**. Examples of such a low-friction material include DLC (diamond-like carbon). As described above, a frictional coefficient of the contact surface between the wafer chuck **19** and the wafer **11** is reduced, and thus, the wafer **11** (the substrate-side pattern area **53**) can be efficiently deformed by heating with the heating light source **50** of the light irradiation unit **2**.

Fourth Embodiment

[0043] Next, a description will be given of an imprint apparatus according to a fourth embodiment of the present invention. In the imprint apparatus of the first embodiment, a description has been given by taking an example in which a frictional force, acting between the rear surface of the wafer **11** corresponding to the substrate-side pattern area **53** and the holding surface of the wafer chuck **19**, is adjusted. In the present embodiment, a description will be given taking an example in which a thermal deformation force acting on the substrate-side pattern area **53** is adjusted, without adjusting the friction force. Since the configuration of the imprint apparatus of the present embodiment is the same as that of the first embodiment, except that the control unit **6** is different in terms of function, a description of the configuration thereof will be omitted, while focusing on the function of the control unit **6**.

[0044] FIG. **6** is a flowchart illustrating the sequence of operations from the mold-pressing step to the curing step performed by the imprint apparatus **1** of the present embodiment. First, the control unit **6** reads the value of the suction pressure of the suction unit **51***b* provided in the wafer chuck **19** after the mold-pressing step (step S**400**). Next, the control unit **6** orders to perform first alignment measurement corresponding to the process in step S**101** shown in FIG. **3** (step S**401**). The control unit **6** calculates the irradiation dose of light irradiated on a wafer, based on the value of the suction pressure of the suction unit **51***b* obtained in step S**400** (step S**402**). Next, the shape of the substrate-side pattern area **543** is corrected by irradiating the wafer **11** with the calculated irradiation dose of light (step S**403**). Then, the displacement input to the mold **7** (step S**404** corresponding to step S**103** shown in FIG. **3**) and the second alignment measurement (step S**405** corresponding to step S**105** shown in FIG. **3**) are executed. When a positional shift is present between the mold **7** and the wafer **11**, position adjustment between the mold **7** and the wafer **11** (step S**406**) is performed. Then, the curing step is performed.

[0045] A description will be given of an irradiation dose to be calculated in step S**402**, with reference to FIG. **7**. The heating mechanism irradiates the irradiation region on the wafer **11**, including at least the substrate-side pattern area **53** with light obtained as the sum of a uniform irradiation dose a and an irradiation dose b having a distribution. Here, the irradiation dose a is a uniform irradiation dose with respect to an irradiation region, in which a thermal deformation force applied to the irradiation region on the wafer **11** in a direction along the plane thereof is greater than the maximum static frictional force acting between the rear surface of the irradiation region on the wafer **11** and the suction unit **51**. The irradiation dose b is an irradiation dose having a distribution with respect to an irradiation region depending on the correction amount of the substrate-side pattern area **53** calculated by the control unit **6**, or depending on the value obtained by subtracting the amount of deformation of the wafer **11** caused by the irradiation dose α from the correction amount.

[0046] It is preferable that the irradiation dose α is determined depending on the suction pressure of the suction unit **51***b* (suction force). When the temperature rise of the substrate-side pattern area **53** is given as "ΔT", the thermal expansion coefficient thereof is given as "α", and the modulus of elasticity thereof is given as "E", all of which are determined depending on the irradiation dose. The thermal stress "σ" can be approximately expressed as the product of σ, E, and ΔT. The thermal deformation force W depending on the thermal stress "σ" and the cross-sectional area "S" acts on the substrate-side pattern area **53**. When the maximum static frictional coefficient is given as "μ" and the vertical directional force depending on the suction pressure is given as "N", the maximum static frictional force F can be expressed as the product of μ and N. In other words, it is only necessary to satisfy the relationship $F<W$. It is preferable that the irradiation dose b is determined on the basis of irradiation dose data prepared in advance, corresponding to the correction amount or the relationship in which the correction amount is associated with the irradiation dose.

[0047] In the present embodiment, although the suction pressure of the suction unit **51** is not adjusted for reducing a frictional force, the wafer **11** is heated by the irradiation of light at the irradiation dose α, such that thermal deformation force does not exceed the maximum static frictional force. Consequently, the shape of the substrate-side pattern area **53** can be efficiently corrected, as in the first embodiment. The present embodiment can be combined with pressure adjustment in the first embodiment.

[0048] (Article Manufacturing Method)

[0049] A method of manufacturing a device (e.g., a semiconductor integrated circuit element, a liquid display element, or the like), as an article, may include a step of forming a pattern on a substrate (e.g., a wafer, a glass plate, a film-like substrate, or the like) using the imprint apparatus described above. Furthermore, the manufacturing method may include a step of etching the substrate on which a pattern has been formed. When other articles, such as a patterned medium (storage medium), an optical element, or the like, is manufactured, the manufacturing method may include other steps of processing the substrate on which a

pattern has been formed, instead of the etching step. The article manufacturing method of the present embodiment has an advantage, as compared with a conventional article manufacturing method, in at least one of performance, quality, productivity, and production cost of an article.

[0050] While the embodiments of the present invention have been described with reference to exemplary embodiments, it is to be understood that the invention is not limited to the disclosed exemplary embodiments. The scope of the following claims is to be accorded the broadest interpretation, so as to encompass all such modifications and equivalent structures and functions.

We claim:

1. An imprint apparatus for forming a pattern of an imprint material on a substrate by using a mold, the imprint apparatus comprising;

a substrate holding unit configured to hold the substrate by acting a suction force between the substrate and a holding surface, the substrate holding unit including a first suction unit for sucking a rear surface of a first region of the substrate with a first suction force and a second suction unit for sucking a rear surface of a second region of the substrate, different from the first region of the substrate, with a second suction force;

a deformation mechanism configured to deform a shape of the first region in a direction along the holding surface when forming the pattern of the imprint material on the first region; and

an adjusting unit configured to adjust the first suction force and the second suction force, wherein the adjusting unit adjusts the first suction force to be less than the second force in at least a portion of a period during the deforming of the shape of the first region by the deformation mechanism.

2. The imprint apparatus according to claim **1**, wherein the adjusting unit adjusts the first suction force to be less than the second force in at least the portion of the period by decreasing the first suction force to be less than a suction force between the substrate and the holding surface when forming the pattern of the imprint material on a region of the substrate different from the first region.

3. The imprint apparatus according to claim **2**, wherein, after the deforming of the shape of the first region into a predetermined shape by the deformation mechanism and prior to a releasing of the mold from the imprint material on the first region, the adjusting unit increases the first suction force.

4. The imprint apparatus according to claim **1**, further comprising an acquiring unit configured to acquire the shape of the first region by detecting a plurality of marks provided on the substrate,

wherein the deformation mechanism deforms the shape of the first region so as to reduce a difference between a shape of a pattern formed on the mold and the shape of the first region.

5. The imprint apparatus according to claim **1**, wherein the deformation mechanism includes a heating mechanism configured to heat the first region.

6. The imprint apparatus according to claim **5**, wherein the deformation mechanism heats the first region by irradiating light to the first region.

7. The imprint apparatus according to claim **6**, wherein the deformation mechanism causes an uneven temperature distribution in the first region by the irradiating light.

8. The imprint apparatus according to claim **4**, further comprising a mold deformation mechanism configured to deform a shape of the mold,

wherein the mold deformation mechanism deforms the shape of the mold and the deformation mechanism deforms the shape of the first region so as to reduce the difference.

9. The imprint apparatus according to claim **1**, wherein, in at least the portion of the period, the adjusting unit decreases a friction force between the first suction unit and the substrate to be less than a friction force between the second suction unit and the substrate.

10. The imprint apparatus according to claim **1**, wherein, in at least the portion of the period, a force to deform the first region by the deformation mechanism is greater than a maximum static friction force acting between the first suction force and the rear surface of the substrate.

11. A method of manufacturing an article, the method comprising steps of:

(a) forming a pattern of an imprint material on a substrate using an imprint apparatus for forming the pattern on the substrate by using a mold;

(b) processing the substrate on which the pattern is formed by the forming; and

(c) manufacturing the article from the processed substrate, wherein the imprint apparatus includes:

(i) a substrate holding unit configured to hold the substrate by acting as a suction force between the substrate and a holding surface, the substrate holding unit including a first suction unit for sucking a rear surface of a first region of the substrate with a first suction force and a second suction unit for sucking a rear surface of a second region of the substrate, different from the first region of the substrate, with a second suction force;

(ii) a deformation mechanism configured to deform a shape of the first region in a direction along the holding surface when forming the pattern of the imprint material on the first region, and

(iii) an adjusting unit configured to adjust the first suction force and the second suction force, wherein the adjusting unit adjusts the first suction force to be less than the second force in at least a portion of a period during the deforming of the shape of the first region by the deformation mechanism.

12. A method of manufacturing an article according to claim **11**, further comprising adjusting, by the adjusting unit, the first suction force to be less than the second force in at least the portion of the period by decreasing the first suction force to be less than a suction force between the substrate and the holding surface when forming the pattern of the imprint material on a region of the substrate different from the first region.

13. A method of manufacturing an article according to claim **12**, wherein, after the deforming of the shape of the first region into a predetermined shape by the deformation mechanism and prior to a releasing of the mold from the imprint material on the first region, and further comprising adjusting the first suction force by the adjusting unit.

14. A method of manufacturing an article according to claim **11**, further comprising acquiring, by an acquiring unit, the shape of the first region by detecting a plurality of marks provided on the substrate,

wherein the deformation mechanism deforms the shape of the first region so as to reduce a difference between a shape of a pattern formed on the mold and the shape of the first region.

15. A method of manufacturing an article according to claim **11**, wherein the deformation mechanism includes a heating mechanism and further comprising heating the first region by the heating mechanism.

16. A method of manufacturing an article according to claim **15**, wherein the deformation mechanism heats the first region by irradiating light to the first region.

17. A method of manufacturing an article according to claim **16**, wherein the deformation mechanism causes an uneven temperature distribution in the first region by the irradiating light.

18. A method of manufacturing an article according to claim **14**, further comprising deforming a shape of the mold, by a mold deformation mechanism, wherein the mold deformation mechanism deforms the shape of the mold and the deformation mechanism deforms the shape of the first region so as to reduce the difference.

19. A method of manufacturing an article according to claim **11**, wherein, in at least the portion of the period, and further comprising adjusting, by the adjusting unit, a friction force between the first suction unit and the substrate to be less than a friction force between the second suction unit and the substrate.

20. A method of manufacturing an article according to claim **11**, wherein, in at least the portion of the period, a force to deform the first region by the deformation mechanism is greater than a maximum static friction force acting between the first suction force and the rear surface of the substrate.

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